

Interconnect Electroplating

Continuous electroplating for stamped and formed contacts



msi is a leading electroplater of continuous strip and progressive stamped and bandoleered components for the connector, electronics and automotive industries. With sixteen multi-finish continuous plating lines operating 24 x 7, quality certifications to ISO9000, AS9000, NADCAP and FAA, **msi** provides state of the art continuous electroplating for today's demanding markets.

msi's custom built continuous electroplating facility processes stamped and formed contacts, bulk strip, wire and individual interconnect bandoleer mounted components for most major connector manufacturers.

Processes

- Copper
- Gold
- Nickel
- Silver
- Tin
- *inhibit-W**
- Tin Lead
- Palladium Nickel

**inhibit-W* is a proprietary continuous plating process that combines custom designed continuous plating lines with the best of chemical solutions to inhibit both crystalline growth and surface oxidation on pure tin deposits.

Plate & Hold.

msi provides a 'plate and hold' inventory system that allows customers to store reeled components in their own 'virtual' inventory in raw condition or plated for immediate release. This system allows for products to be received directly from the stamping or component supplier and does not impact customers inventory value with additional plating cost until required. Scheduled weekly shipments throughout the USA or individual releases can compliment JIT and Lean Manufacturing programs. Web based access for inventory and schedule verification is being provided.

Process Trials.

msi will process sample reels for customer evaluation. PPAP procedures are available as required for initial process runs.

